

**Amendments to the Specification**

Please amend paragraph [0002] as follows:

[0002] “Cooling System and Method Employing At Least Two Modular Cooling Units For Ensuring Cooling Of Multiple Electronics Subsystems,” Chu et al., (~~Decket No. POU920030166US1~~), Serial No. ~~\_\_\_\_\_~~, co-filed herewith Serial No. 10/726,377, filed December 3, 2003; and

Please amend paragraph [0003] as follows:

[0003] “Scalable Coolant Conditioning Unit with Integral Plate Heat Exchanger/Expansion Tank and Method of Use,” Chu et al., Serial No. 10/243,708, filed September 13, 2002, which issued on March 30, 2004 as United States Letters Patent No. 6,714,412.